July 17, 2012

CN Number: 1210

CN Change Level: Minor

Subject: Extra Bond Pad on 42MX Die

Dear Customer,

The purpose of this CN is to advise that an additional pad was added to the new revision of all 42MX devices for internal test coverage improvements. This pad is not exposed to packaged parts and is only visible at the die level. This change has no impact on the functionality or the reliability of the product. The extra pad is show in the bottom left hand corner of the layout in Figure 1 (highlighted in black).

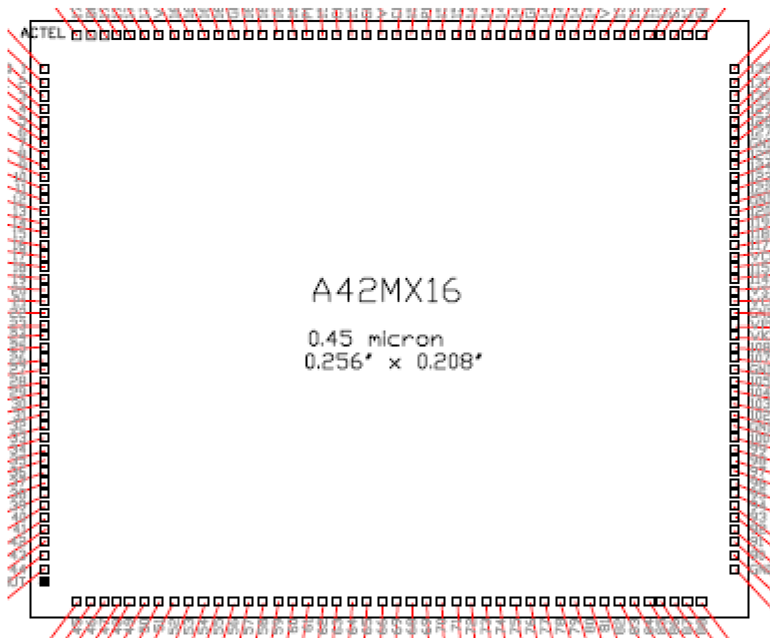

Figure 1: Extra Bond Pad on A42MX16 Device

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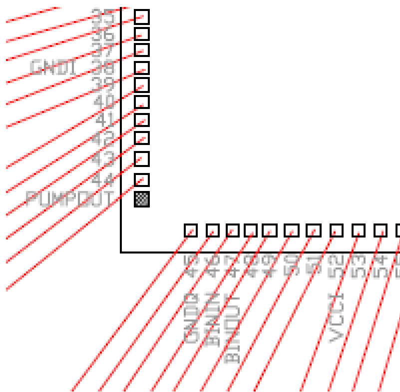

Figure 2: Extra Bond Pad Detail

If you have any questions, please contact Microsemi SoC Products Group Technical Support at soc_tech@microsemi.com.

Regards,

Microsemi Corporation

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